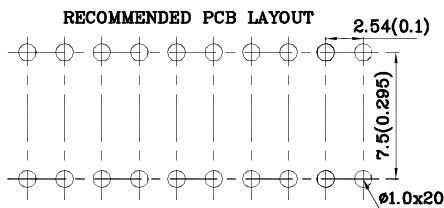
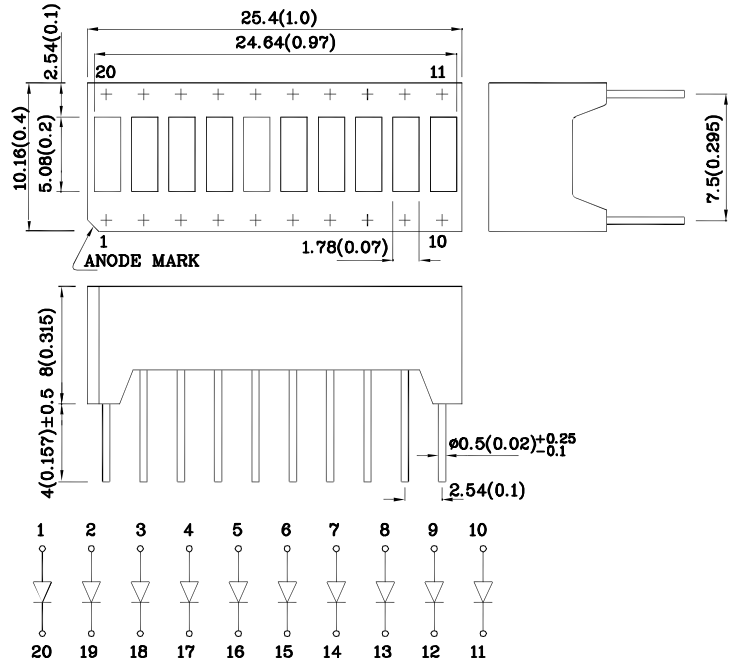


Features

- Robust package
- Uniform light disbursement
- Ideal for backlighting logos or icons
- Excellent for flush mounting
- Standard configuration: Gray face w/ white segments
- RoHS compliant



Package Schematics



Notes:

1. All dimensions are in millimeters (inches), Tolerance is ±0.25(0.01") unless otherwise noted.
2. Specifications are subject to change without notice.

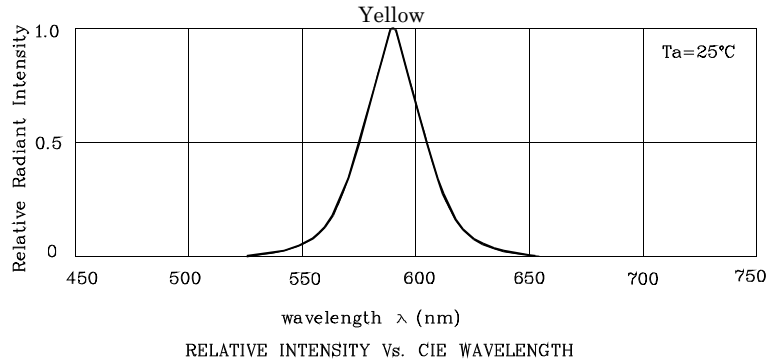
Absolute Maximum Ratings (T _A =25°C)		Yellow (GaAsP/GaP)	Unit
Reverse Voltage	V _R	5	V
Forward Current	I _F	30	mA
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	i _{FS}	140	mA
Power Dissipation	P _D	75	mW
Operating Temperature	T _A	-40 ~ +85	°C
Storage Temperature	T _{stg}	-40 ~ +85	
Lead Solder Temperature [2mm Below Package Base]	260°C For 3-5 Seconds		

A Relative Humidity between 40% and 60% is recommended in ESD-protected work areas to reduce static build up during assembly process (Reference JEDEC/JESD625-A and JEDEC/J-STD-033)

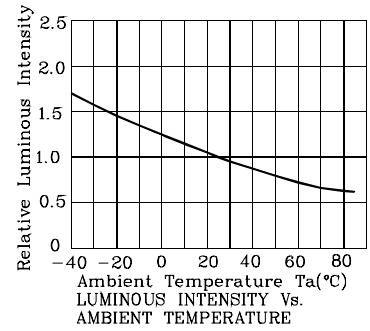
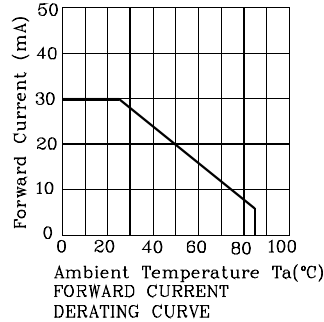
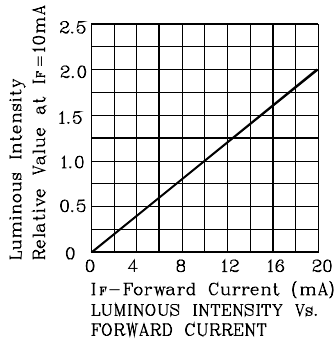
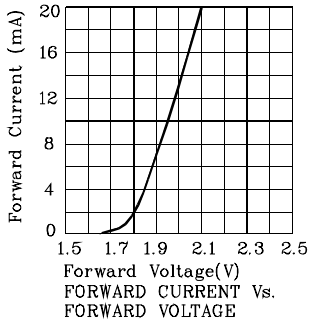
Operating Characteristics (T _A =25°C)		Yellow (GaAsP/GaP)	Unit
Forward Voltage (Typ.) (I _F =10mA)	V _F	1.95	V
Forward Voltage (Max.) (I _F =10mA)	V _F	2.5	V
Reverse Current (Max.) (V _R =5V)	I _R	10	uA
Wavelength of Peak Emission CIE127-2007* (Typ.) (I _F =10mA)	λ _P	590*	nm
Wavelength of Dominant Emission CIE127-2007* (Typ.) (I _F =10mA)	λ _D	588*	nm
Spectral Line Full Width At Half-Maximum (Typ.) (I _F =10mA)	Δλ	35	nm
Capacitance (Typ.) (V _F =0V, f=1MHz)	C	20	pF

Part Number	Emitting Color	Emitting Material	Luminous Intensity CIE127-2007* (I _F =10mA) ucd		Wavelength CIE127-2007* nm λ _P	Description
			min.	typ.		
XGUYX10D	Yellow	GaAsP/GaP	2200 900*	8990 2390*	590*	10 Segments Bar graph-Display

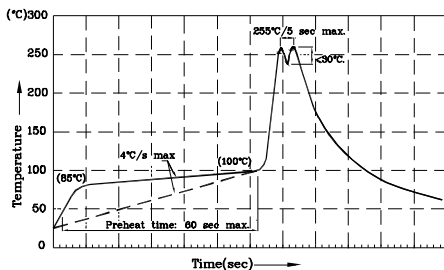
*Luminous intensity value and wavelength are in accordance with CIE127-2007 standards.



❖ Yellow



Wave Soldering Profile for Thru-Hole Products (Pb-Free Components)



- Notes:
- 1.Recommend pre-heat temperature of 105°C or less (as measured with a thermocouple attached to the LED pins) prior to immersion in the solder wave with a maximum solder bath temperature of 260°C
 - 2.Peak wave soldering temperature between 245°C ~ 255°C for 3 sec (5 sec max).
 - 3.Do not apply stress to the epoxy resin while the temperature is above 85°C.
 - 4.Fixtures should not incur stress on the component when mounting and during soldering process.
 - 5.SAC 305 solder alloy is recommended.
 - 6.No more than one wave soldering pass.
 - 7.During wave soldering, the PCB top-surface temperature should be kept below 105°C.

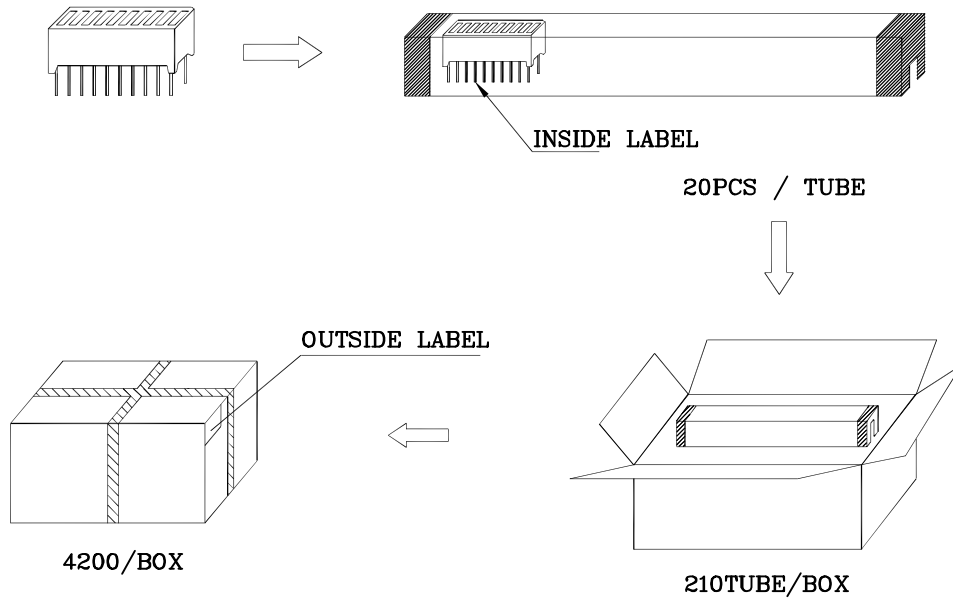
Remarks:

If special sorting is required (e.g. binning based on forward voltage, luminous intensity / luminous flux, or wavelength), the typical accuracy of the sorting process is as follows:

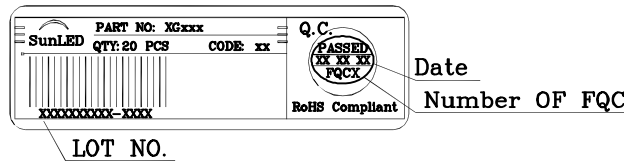
1. Wavelength: +/-1nm
2. Luminous Intensity / Luminous Flux: +/-15%
3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.

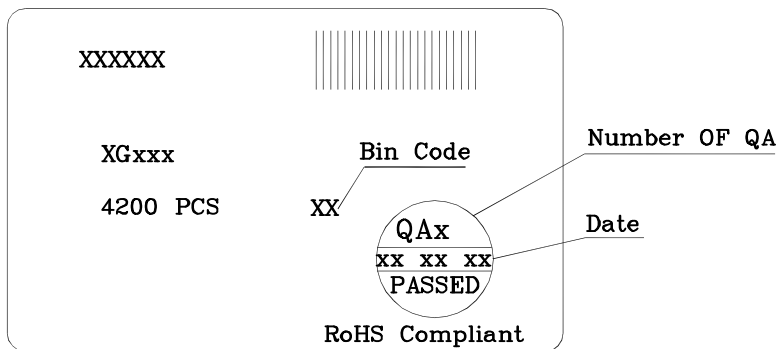
PACKING & LABEL SPECIFICATIONS



Inside Label On IC-tube



Outside Label On Box



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2. Contents within this document are subject to improvement and enhancement changes without notice.
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